

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>George Lin</td><td>03/10/2009</td></tr><tr><td>Ming-Hsiung Fu</td><td>03/10/2009</td></tr></tbody></table>	Name	Execution Date	George Lin	03/10/2009	Ming-Hsiung Fu	03/10/2009	
Name	Execution Date						
George Lin	03/10/2009						
Ming-Hsiung Fu	03/10/2009						
RECEIVING PARTY DATA							
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.						
Street Address:	No. 8, Li-Hsin, Rd. 6, Science-Based Industrial Park						
City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12414373</td></tr></tbody></table>	Property Type	Number	Application Number:	12414373			
Property Type	Number						
Application Number:	12414373						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Liem T. Do						
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PATENT

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REEL: 022470 FRAME: 0649

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|---|
| (1) | George Lin | of | No. 56-67, Xiao Xin Yin, Xiao Xin Village
Shan Hua Township, Tainan County, Taiwan, R.O.C. |
| (2) | Ming-Hsiung Fu | of | 9F, No. 112, Shengli 2nd Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C. |

have invented certain improvements in

WAFER PROCESS CHAMBER LEAK DETECTOR

for which we have executed an application for Letters Patent of the United States of America on March 30, 2009, as U.S. Serial No. 12/414,373; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2008-0651 / 24061.1200

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: George Lin

Residence Address: No. 56-67, Xiao Xin Yin, Xiao Xin Village
Shan Hua Township, Tainan County, Taiwan, R.O.C.

Dated: ✓ March 10, 2009

✓ 林育聰, George Lin
Inventor Signature

Inventor Name: Ming-Hsiung Fu

Residence Address: 9F, No. 112, Shengli 2nd Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: ✓ March 10, 2009

✓ 傅明興 Ming Hsiung, Fu
Inventor Signature